



PRIME compliant Power Line Communications Modem

SUMMARY DATASHEET

Features

- Modem
 - Power Line Carrier Modem for 50 and 60 Hz mains
 - 97-carrier OFDM PRIME compliant
 - Baud rate Selectable: 21400 to 128600 bps
 - Differential BPSK, QPSK, 8-PSK modulations
- Memory
 - 32Kbytes on-chip SRAM
- Automatic Gain Control and signal amplitude tracking
- Embedded on-chip DMAs
- Media Access Control
 - Viterbi decoding and CRC PRIME compliant
 - 128-bit AES encryption
 - · Channel sensing and collision pre-detection
- Package
 - 120-lead LQFP, 14 x 14 mm, pitch 0.4 mm
 - Pb-free and RoHS compliant
- Typical Applications
 - Automated Meter Reading (AMR) & Advanced Meter Management (AMM)
 - Street lighting
 - Home Automation

Description

ATLP220A is a PRIME (Powerline-Related Intelligent Metering Evolution) compliant ASIC specifically designed for PLC Base Nodes implementation. Systems using this ASIC support both mono-phase and multi-phase PLC injection. Mono-phase injection is achieved by means of a single ATLP220A ASIC, whereas several ATLP220A can be combined to achieve multi-phase injection based on Atmel MIMO technology.

The combination of multi-phase injection and Atmel MIMO technology increases PRIME Base Nodes performance, resulting in outstanding robustness and network coverage.

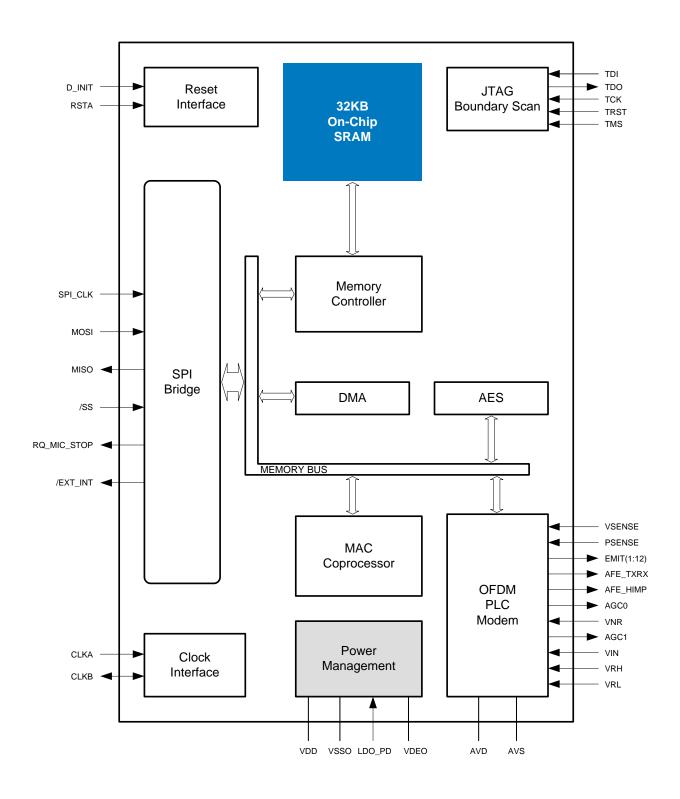
ATLP220A has been conceived to be easily managed by an external microcontroller by means of an SPI interface. The external microcontroller implements Base Node upper layers (as specified in PRIME) while ATLP220A carries out PHY layer functionalities.

Line Coupling front end design is extremely simplified, bringing off a very low cost bill of materials.



1. Block Diagram

Figure 1-1. ATPL220A 120-pin Block Diagram

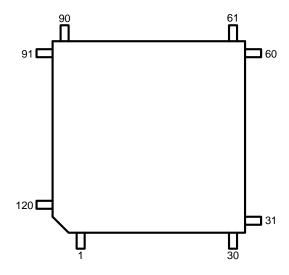




2. Package and Pinout

2.1 **120-Lead LQFP Package Outline**

Figure 2-1. Orientation of the 120-Lead Package





2.2 120-Lead LQFP Pinout

Table 2-1. ATPL220A 120-Lead LQFP pinout

1	NC	
2	NC	
3	GND	
4	VCC	
5	NC	
6	NC	
7	NC	
8	NC	
9	NC	
10	NC	
11	NC	
12	NC	
13	NC	
14	VCC	
15	GND	
16	VDD	
17	NC	
18	NC	
19	NC	
20	NC	
21	NC	
22	NC	
23	NC	
24	NC	
25	NC	
26	GND	
27	VCC	
28	NC	
29	NC	
30	MISO	

31	MOSI	
32	SPICLK	
33	/SS	
34	RQ_MIC_STOP	
35	/EXT_INT	
36	VCC	
37	GND	
38	EMIT.1	
39	EMIT.2	
40	EMIT.3	
41	EMIT.4	
42	VCC	
43	GND	
44	EMIT.5	
45	EMIT.6	
46	EMIT.7	
47	EMIT.8	
48	VCC	
49	GND	
50	EMIT.9	
51	EMIT.10	
52	EMIT.11	
53	EMIT.12	
54	VCC	
55	GND	
56	AFE_HIMP	
57	AFE_TXRX	
58	VSENSE	
59	PSENSE	
60	VNR	

61	TDI	
62	TMS	
63	TDO	
64	GND	
65	GND	
66	VCC	
67	TRST	
68	TCK	
69	RSTA	
70	D_INIT	
71	GND	
72	VCC	
73	GND	
74	VDD	
75	LDO_PD	
76	VSS0	
77	VDE0	
78	VDE0	
79	GND	
80	GND	
81	VCC	
82	CLKEA	
83	GND	
84	CLKEB	
85	VCC	
86	NC	
87	NC	
88	NC	
89	NC	
90	NC	

91	NC		
92	NC		
93	GND		
94	AGC1		
95	AGC0		
96	GND		
97	VCC		
98	AVS2		
99	AVD2		
100	AVS1		
101	AVD1		
102	VRH		
103	VIN		
104	VRL		
105	GND		
106	VCC		
107	NC		
108	NC		
109	NC		
110	NC		
111	NC		
112	NC		
113	NC		
114	GND		
115	VCC		
116	NC		
117	NC		
118	NC		
119	NC		
120	NC		



3. Mechanical Characteristics

Figure 3-1. 120-lead LQFP Package Mechanical Drawing

120-pin plastic LQFP

Lead pitch 0.40 mm

Pa ckage width × package length 14.0 mm × 14.0 mm

Lead shape Gullwing

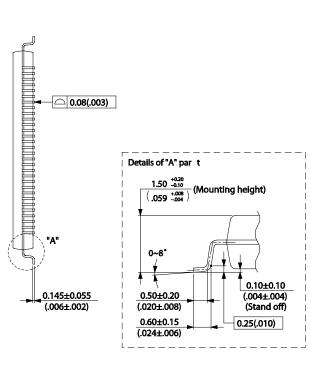
Sealing method Plastic mold

Mounting height 1.70 mm MAX

Code (Ref erence) P-LFQFP120-14 ×14-0.4 0

120-pin plastic LQFP

- Note 1) *: These dimensions do not include resin protrusion.
- Note 2) Pins width and pins thickness include plating thickness.
- Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches). Note: The values in parentheses are reference values.



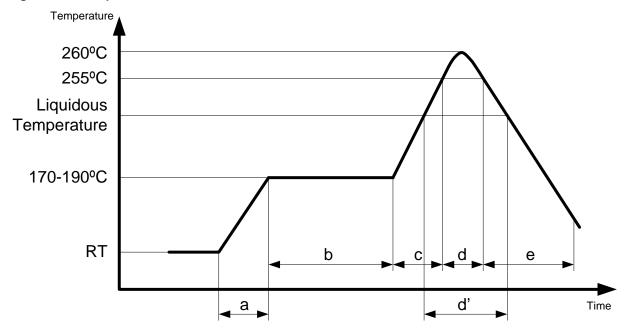
4. Recommended mounting conditions

4.1 Conditions of Standard Reflow

Table 4-1. Conditions of standard Reflow

Items	Contents	
Method	IR(Infrared Reflow)/Convection	
Times	2	
Floor Life	Before unpacking	Please use within 2 years after production
	From unpacking to second reflow	Within 8 days
	In case over period of floor life	Baking with 125°C +/- 3°C for 24hrs +2hrs/-0hrs is required. Then please use within 8 days. (please remember baking is up to 2 times)
Floor Life Condition	Between 5°C and 30°C and also below 70%RH required. (It is preferred lower humidity in the required temp range.)	

Figure 4-1. Temperature Profile



Note: H rank: 260°C Max

a: Average ramp-up rate: 1°C/s to 4°C/s

b: Preheat & Soak: 170°C to 190°C, 60s to 180s

c: Average ramp-up rate: 1°C/s to 4°C

d: Peak temperature: 260°C Max, up to 255°C within 10s

d': Liquidous temperature: Up to 230°C within 40s or

Up to 225°C within 60s or

Up to 220°C within 80s

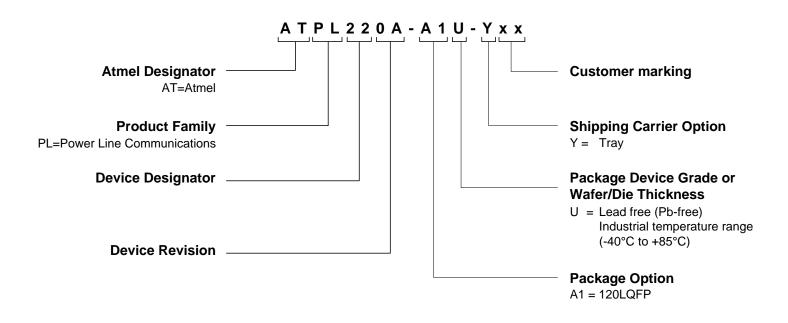
e: Cooling: Natural cooling or forced cooling



5. Ordering Information

Table 5-1. Atmel ATPL220A Ordering Codes

Atmel Ordering Code	Package	Package Type	Temperature Range
ATPL220A-A1U-Y	120 LQFP	Pb-Free	Industrial (-40°C to 85°)





6. Revision History

Doc. Rev.	Date	Comments
1.00	30/03/2012	Initial release





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